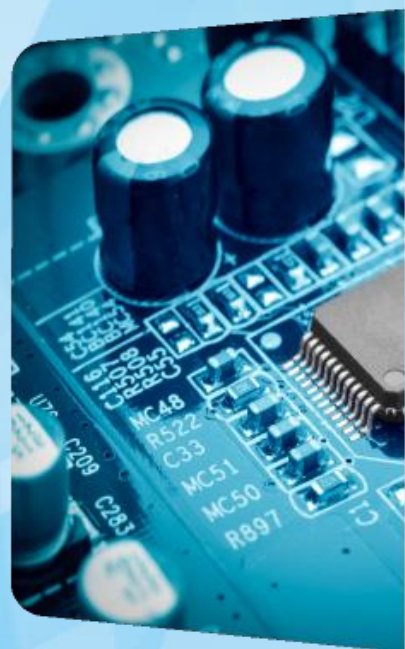
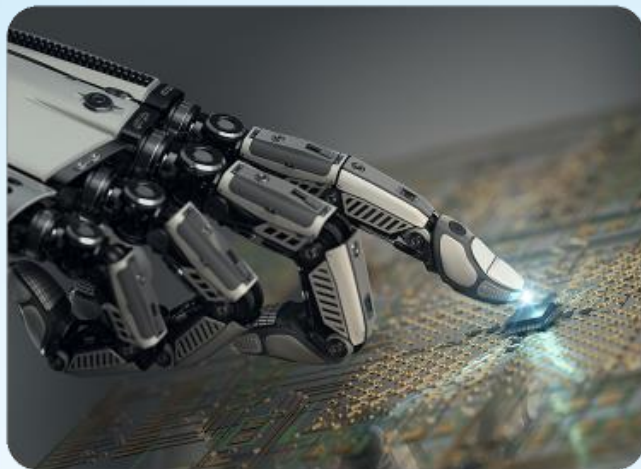




# 善用IEEE開放取用提升學術影響力

何丹丹, IEEE大中華區客戶與資訊經理

杜欣穎 Cindy Tu, Hinton產品&行銷經理



# 主要内容

- 如何提升自己科研的可見度和影響力
- 在IEEE期刊發表開放取用文章的益處
- IEEE 2023 OA 投稿優惠詳解與實踐流程



# 關於 IEEE

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# 如何提高自己科研的可見度和影響力

問題提出

發表論文

研究實施與結果收集

**完整科研流程應該包含哪些步驟？**

研究設計

**推廣研究**

文獻調研

撰寫論文

# 在科研全流程提升研究可見度

- 清晰簡潔的標題，突出讀者可能的興趣點
- 精准、標準化的關鍵字
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- 將論文提交給有影響力的學術機構發表
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Winnie N. Ye  

Also published under: Winnie Ye, W. N. Ye, W. Ye

作者姓名消歧

## Affiliation

Department of Electronics  
1125 Colonel By Drive  
Carleton University, Ottawa, Canada

## Publication Topics

integrated optics, diffraction gratings, silicon, elemental semiconductors, optical waveguides, silicon-on-insulator, integrated optoelectronics, optical communication equipment, beam steering, demultiplexing, micro-optics, optical

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## Biography

Winnie N. Ye (Senior Member, IEEE) received the B.Eng. degree in electrical engineering from Carleton University, Ottawa, ON, Canada, the M.A.Sc. degree in photonics from the University of Toronto, Toronto, ON, and the Ph.D. degree in photonics from Carleton University. She is currently a Full Professor with the

Publications

52

Citations?

338

Publications by Year



## Co-Authors:

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投稿人: Daniel Benedikovič; Qiankun Liu; Alejandro Sánchez-Postigo; Ahmad Atieh; Tom Smy; Pavel Cheben; Winnie N. Ye

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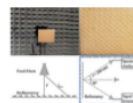
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Usman Sarwar; Muhammad Amin; Dragos Dancila; Imran Aziz

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INSPEC Accession Number: 21012216

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**Publisher:** IEEE [Cite This](#) [PDF](#)

Francisco Nunes ; Pedro Madureira ; Sílvia Rêgo ; Cristiana Braga ; Rúben Moutinho ; Tia... [All Authors](#)

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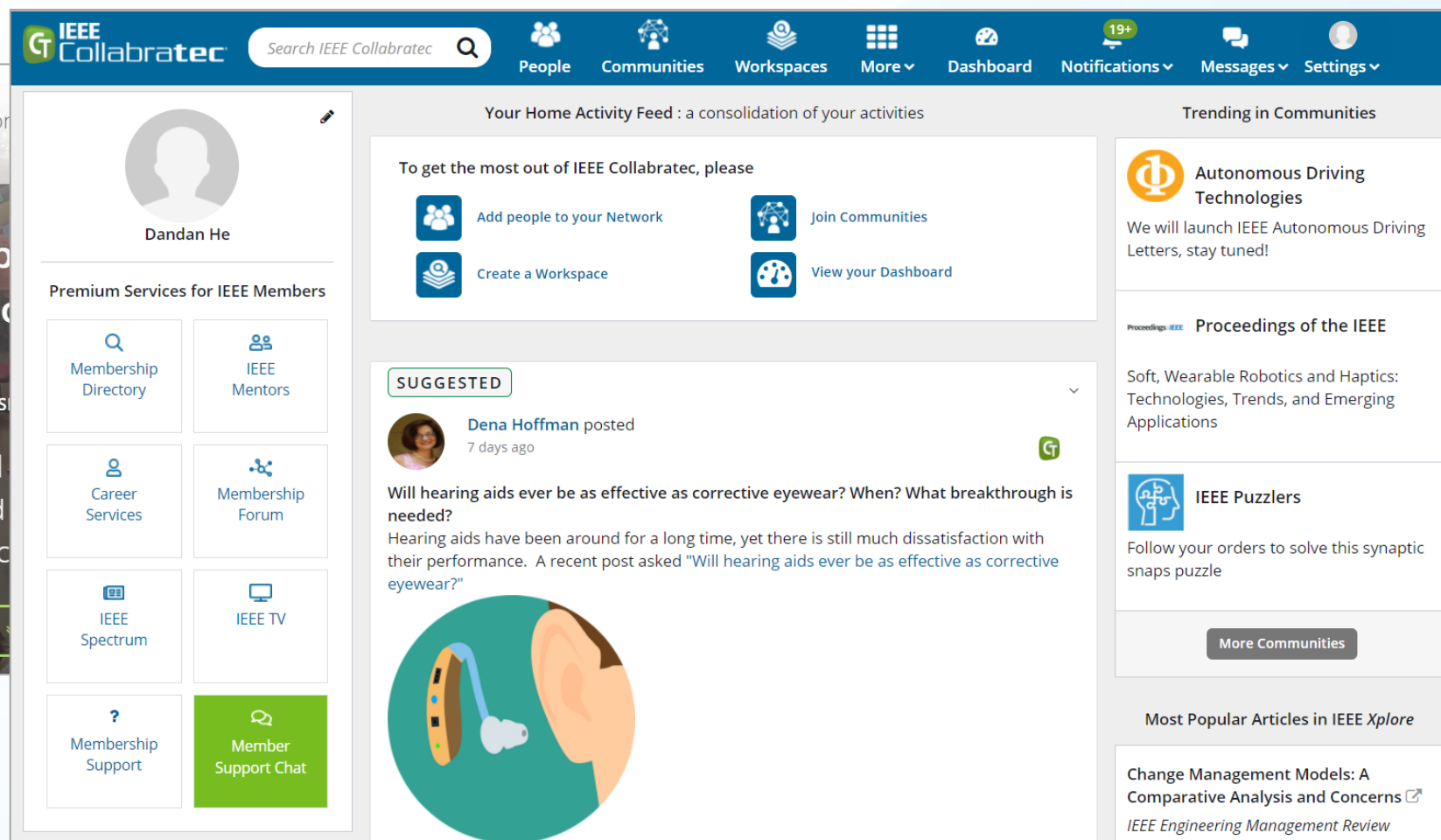
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Authors

Francisco Nunes; Pedro Madureira; Sílvia Rêgo; Cristiana Braga; Rúben Moutinho; Tiago Oliveira; Filipe Soares

# 多途徑推廣學術成果

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- Title of journal or magazine
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  - How it will impact humanity or our everyday lives

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DATELINE, DATE -- Researchers at [organization name] have published their findings on [Area of technology researched (non-technical description) and why it matters] in the latest issue of [IEEE Journal Name, or IEEE Access]. IEEE is the world's largest technical professional organization advancing technology for humanity.

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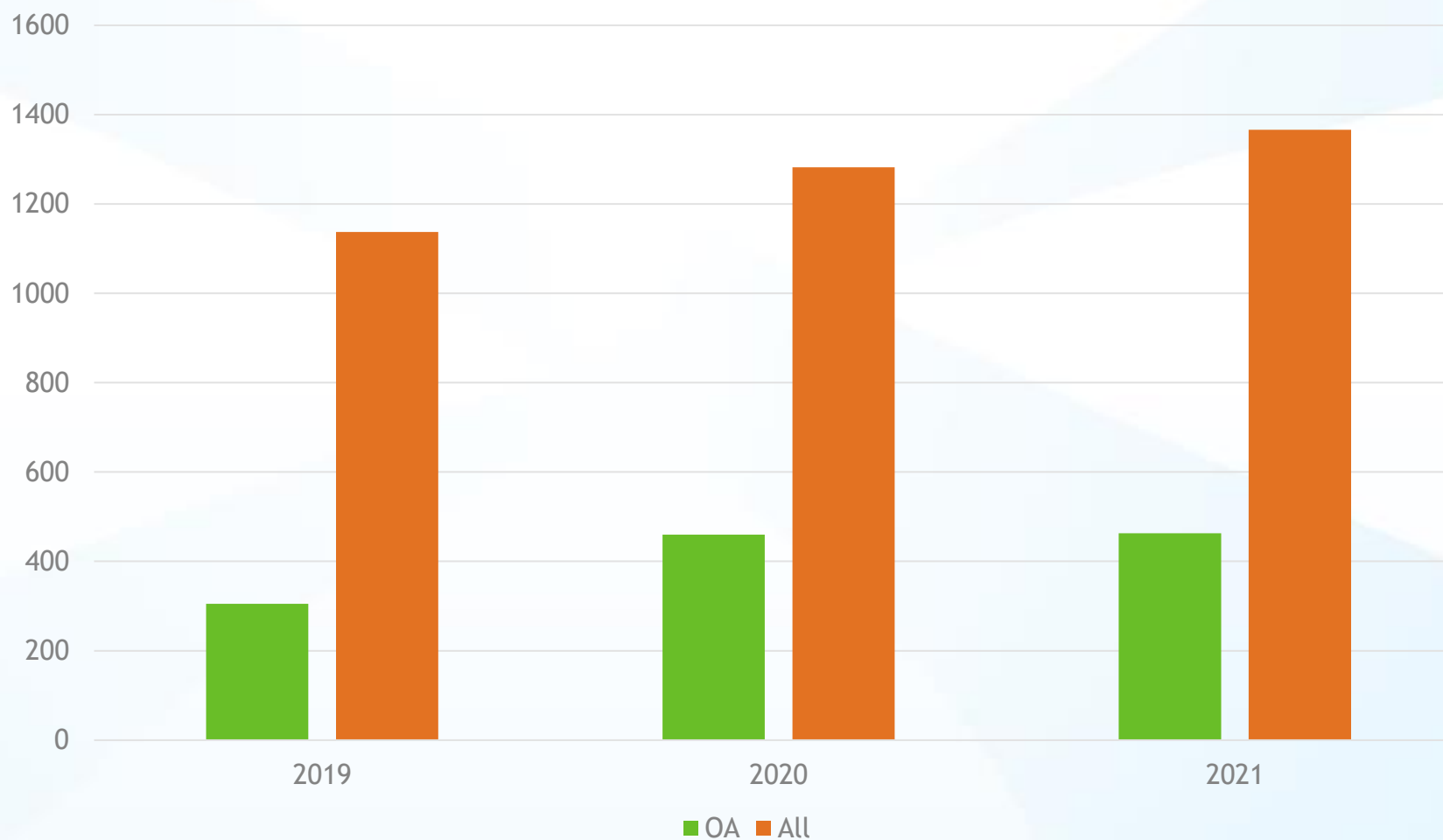
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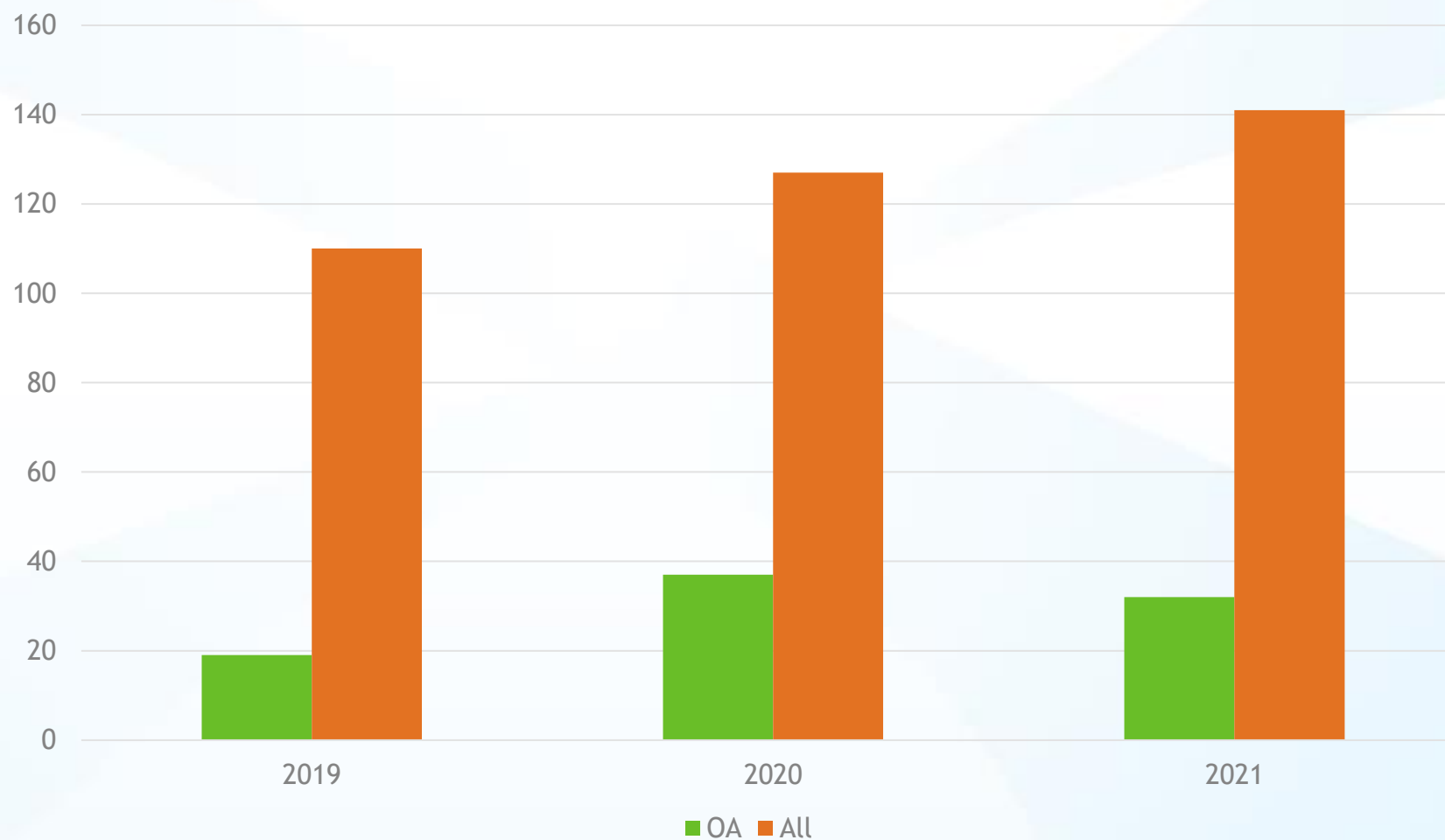
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# 2022 Top OA Titles in Taiwan

## Ranking

## OA Journal Title

- 1 IEEE Access
- 2 IEEE Journal of the Electron Devices Society
- 3 IEEE Photonics Journal
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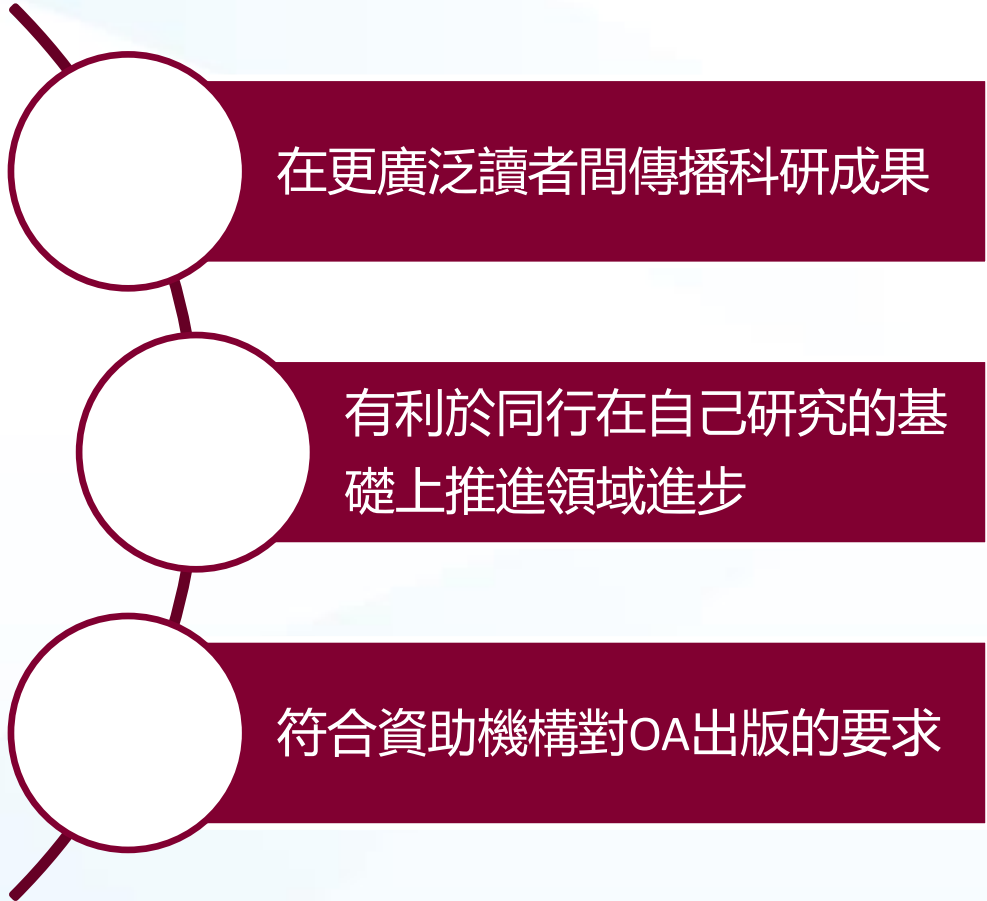


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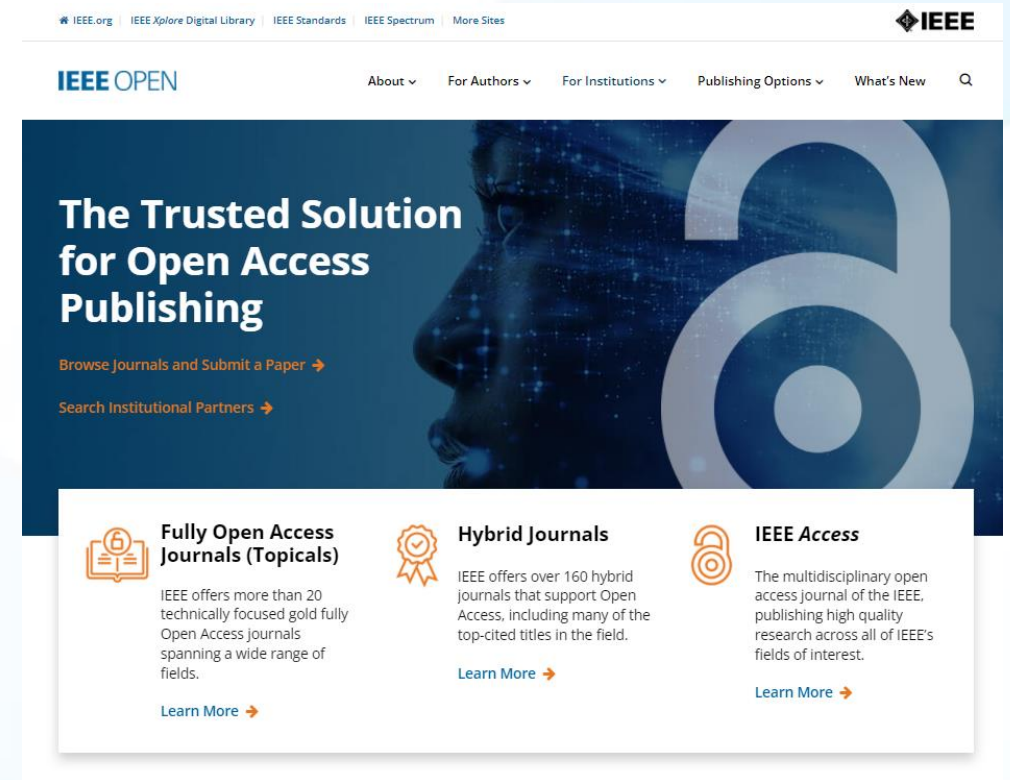
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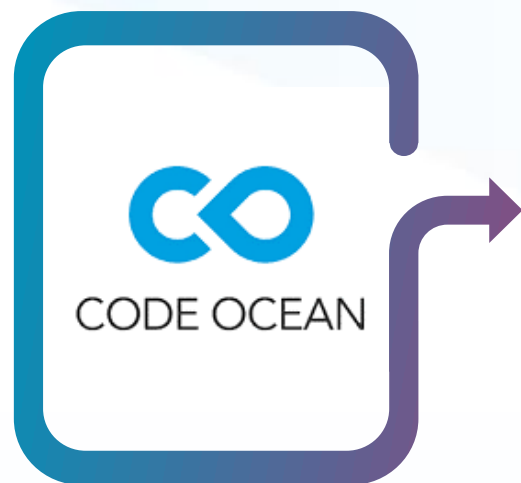
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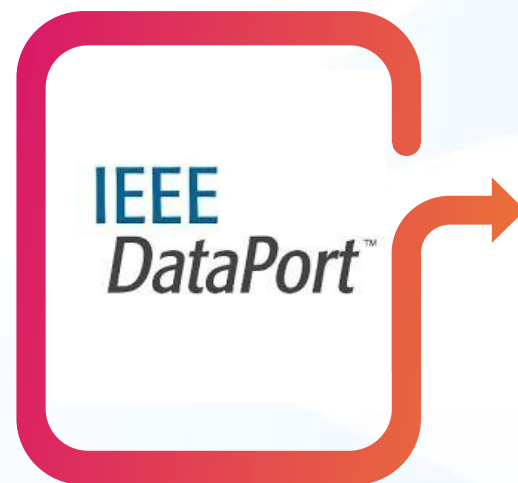
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## Index Modulation Based Coordinate Interleaved Orthogonal Design for Secure Communications

Publisher: IEEE

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Burak Ozpoyraz ; Ibrahim Yildirim ; Ertugrul Basar All Authors

### 文章細節頁面

#### Abstract

#### Document Sections

#### I. Introduction

#### II. System Model

#### III. Performance Analysis

#### IV. Simulation Results

#### V. Conclusion

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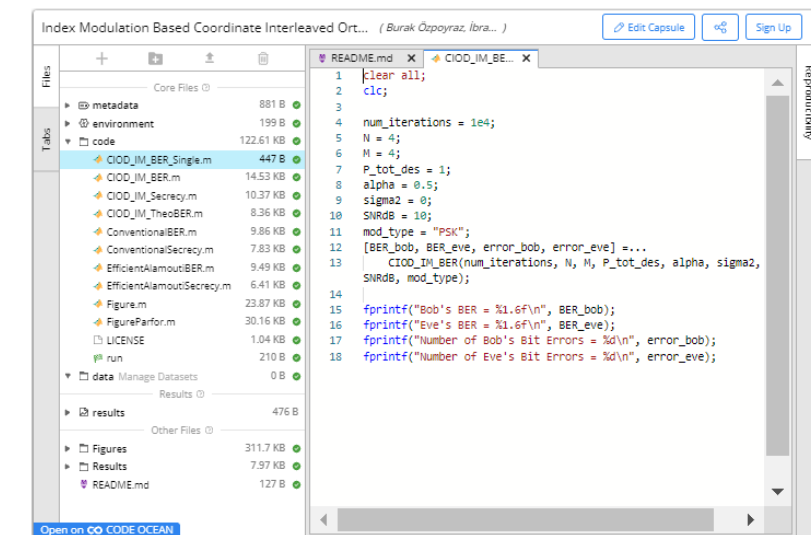
In this paper, we propose a physical layer security scheme that exploits a novel index modulation (IM) technique for coordinate interleaved orthogonal designs (CIOD). Utilizing the diversity gain of CIOD transmission, the proposed scheme, named CIOD-IM, provides an improved spectral efficiency by means of IM. In order to provide a satisfactory secrecy rate, we design a particular artificial noise matrix, which does not affect the performance of the legitimate receiver, while deteriorating the performance of the eavesdropper. We derive expressions of the ergodic secrecy rate and the theoretical bit error rate upper bound. In addition, we analyze the case of imperfect channel estimation by taking practical concerns into consideration. It is shown via computer simulations that the proposed scheme outperforms the existing IM-based schemes and might be a candidate for future secure communication systems.

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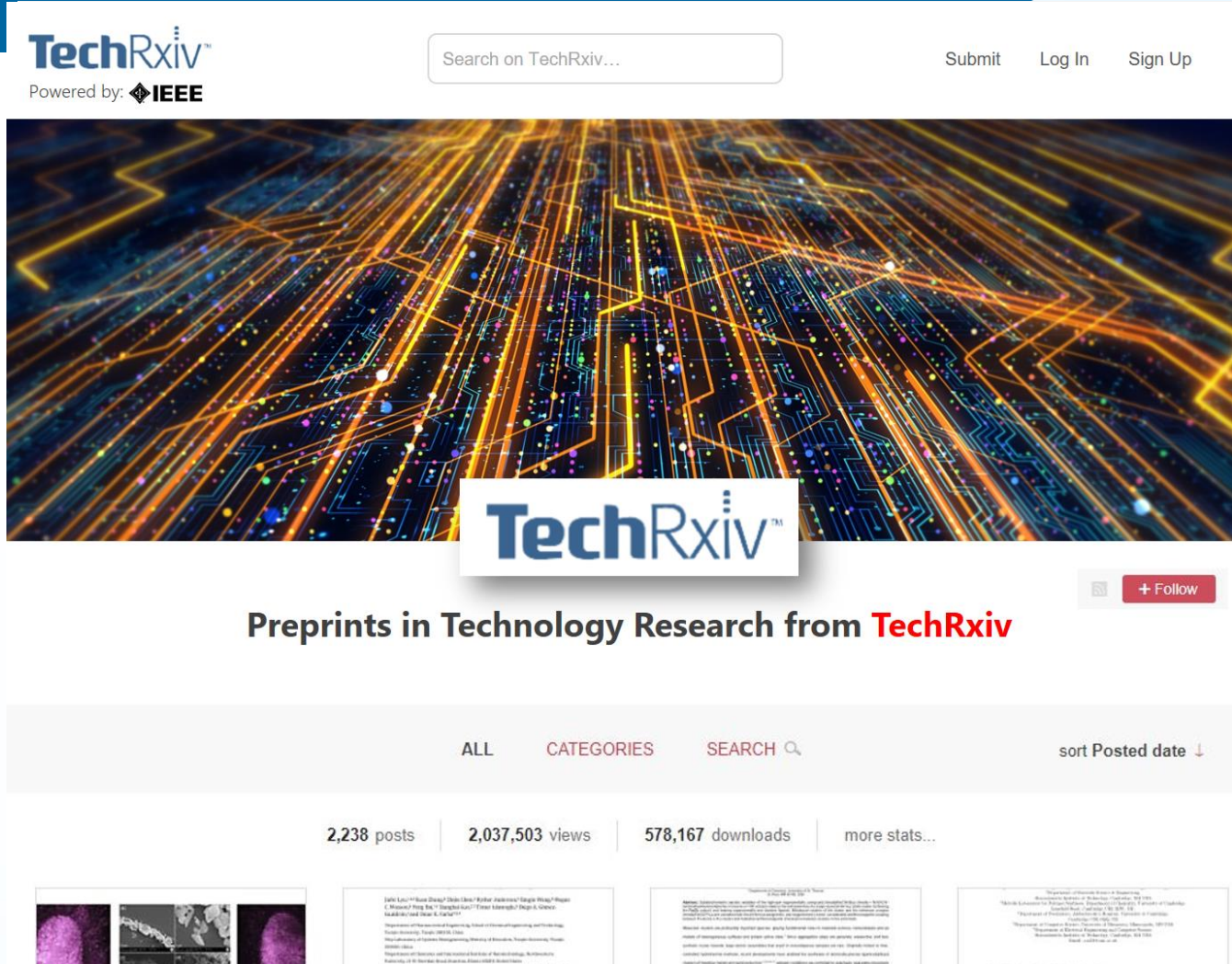
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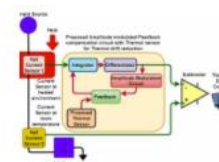
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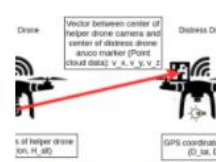
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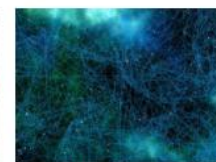
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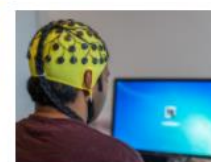
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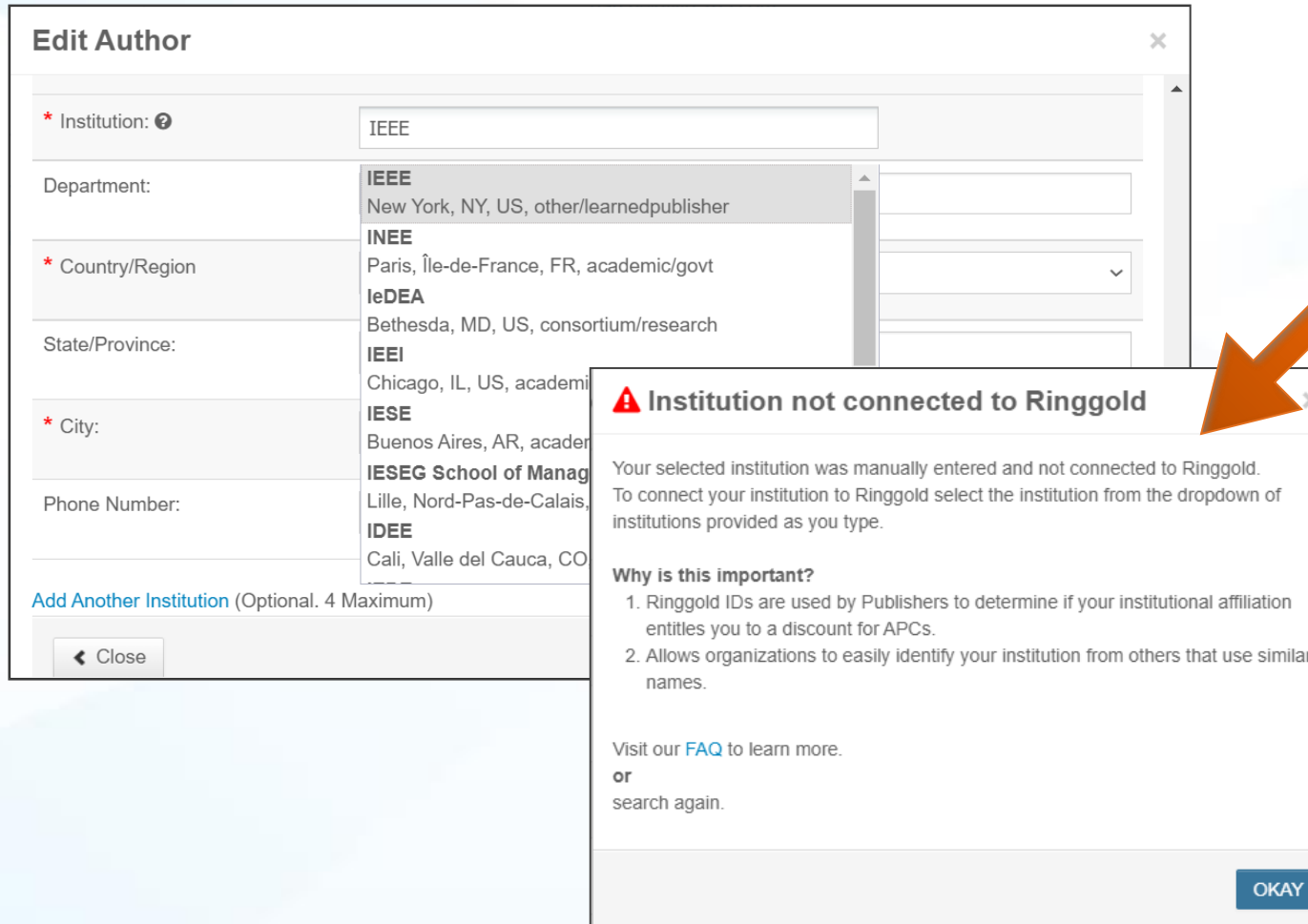
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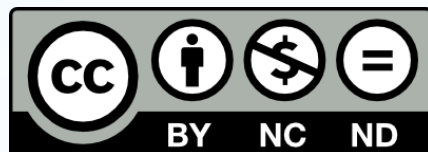
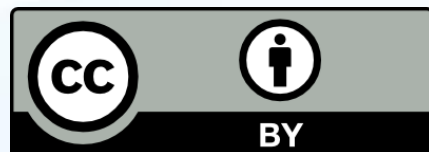
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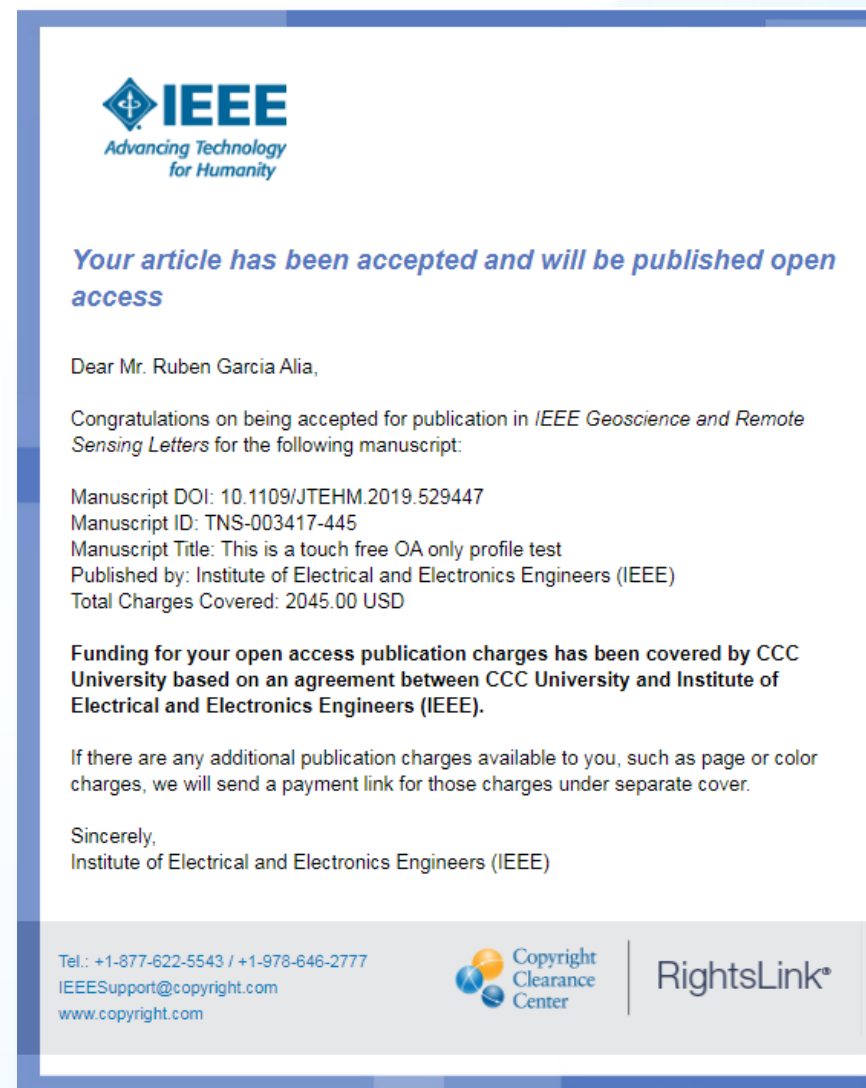
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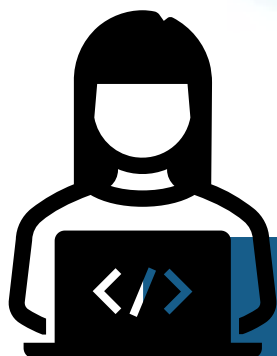


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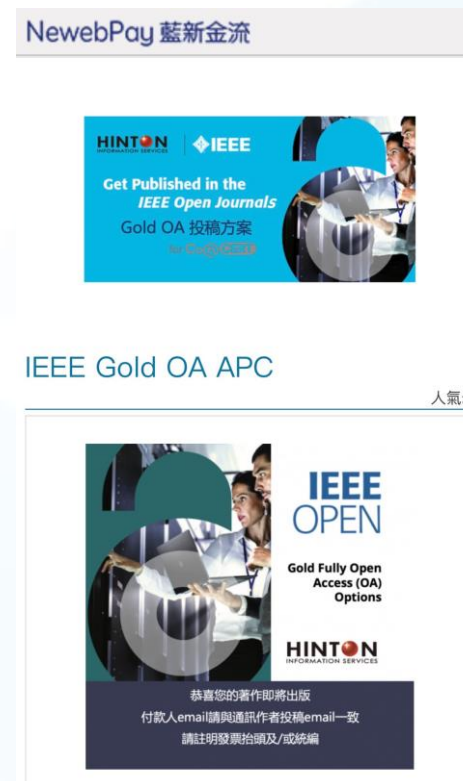
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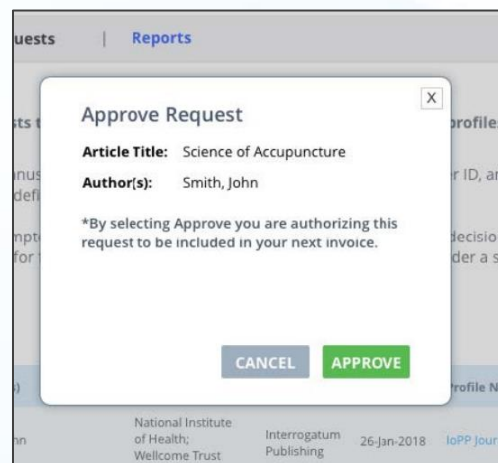
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